

CLAIMS

What is claimed is:

- 1 1. A method of fabricating an electronic package, the method comprising:
2 securing a die to an interposer;
3 securing a laminated conductor to the interposer to supply current to the die
4 and mechanically support the interposer.
- 1 2. The method recited in claim 1, wherein securing a laminated conductor to
2 the interposer includes securing a positive portion of the laminated conductor to a
3 positive section of the interposer and securing a negative portion of the laminated
4 conductor to a negative section of the interposer.
- 1 3. The method recited in claim 1, wherein securing the laminated conductor to
2 the interposer includes securing the laminated conductor to the interposer on a side
3 of the interposer that includes the die.
- 1 4. The method recited in claim 3, wherein securing the laminated conductor to
2 the interposer includes securing the laminated conductor adjacent to the die.
- 1 5. The method recited in claim 1, wherein securing the laminated conductor to
2 the interposer includes soldering the laminated conductor to a surface on the
3 interposer using reflowable solder balls to establish an electrical connection.
- 1 6. The method recited in claim 5, wherein soldering the laminated conductor to
2 the surface on the interposer includes underfilling areas between the laminated
3 conductor and the interposer with an epoxy.

1 7. An electronic package comprising:
2 an interposer;
3 a die secured to the interposer; and
4 a laminated conductor secured to the interposer to mechanically support the
5 interposer and supply current to the die.

1 8. The electronic package of claim 7, wherein the interposer is a composite
2 metal and organic material.

1 9. The electronic package of claim 7, wherein the interposer includes an upper
2 surface and a lower surface and the die and the laminated conductor are secured to
3 the upper surface of the interposer with the laminated conductor adjacent to the die.

1 10. The electronic package of claim 7, further comprising an electronic
2 component secured to the lower surface of the die, the interposer being thin enough
3 to reduce the inductive loop between the electronic component and the die.

1 11. The electronic package of claim 7, wherein the laminated conductor includes
2 a positive portion that is connected to a positive section of the interposer and a
3 negative portion that is connected to a negative section of the interposer.

1 12. The electronic package of claim 7, wherein the laminated conductor includes
2 a pair of conducting sheets separated by a dielectric layer.

1 13. The electronic package of claim 12, wherein one of the sheets includes an
2 opening and the other sheet includes a projection that extends into the opening.

1 14. The electronic package of claim 13, wherein the sheet with the openings
2 includes an exposed surface and the projection includes a tip that is substantially
3 aligned with the exposed surface.

1 15. The electronic package of claim 14, wherein the exposed surface and the tip
2 of the projection are engaged with the interposer.

1 16. The electronic package of claim 7, wherein an end of the laminated
2 conductor is folded over such that each of the sheets engages the interposer.

1 17. The electronic package of claim 7, wherein the interposer has a thickness
2 that is less than 1 mm.

1 18. A computer system comprising:
2 a bus;
3 a memory coupled to the bus;
4 a processor; and
5 a package including an interposer and a laminated conductor secured to the
6 interposer, the processor being secured to the interposer such that the laminated
7 conductor electrically connects the processor to the bus and mechanically supports
8 the interposer during operation of the computer system.

1 19. The computer system of claim 18, wherein the interposer has a thickness less
2 than 1 mm.

1 20. The computer system of claim 18, wherein the laminated conductor and the
2 processor are secured to a common side of the interposer.